



# LM3658 Dual Source USB/AC Li Chemistry Charger IC for Portable Applications

Check for Samples: LM3658

### **FEATURES**

- Integrated power FETs with thermal regulation
- Charges from either an AC wall adapter or USB power source with automatic source selection
- 50 mA to 1000 mA charge currents using AC wall adapter
- Pin-selectable USB charge currents of 100 mA or 500 mA
- LDO mode with 1A of source current is automatically invoked when the battery is absent and the AC wall adapter is connected
- · Continuous battery temperature monitoring
- Built-in multiple safety timers
- Charge status indication
- Continuous over-current and temperature protection

- Near-depleted battery pre-conditioning
- Sleep mode with ultra low quiescent current
- On-board Kelvin-sensing achieves ±0.35% termination accuracy
- Maintenance mode with automatic recharge
- Thermally enhanced 3 mm x 3 mm LLP package

### **APPLICATIONS**

- Smartphones
- Digital still cameras
- PDAs
- Hard Drive and flash-based MP3 players
- USB-powered devices

# **DESCRIPTION**

The LM3658 is a single chip charger IC designed for handheld applications. It can safely charge and maintain a single cell Li-Ion/Polymer battery operating from an AC wall adapter or USB power source. Input power source selection of USB/AC is automatic. With both power sources present, the AC power source has priority. Charge current is programmed through an external resistor when operating from an AC wall adapter allowing charge currents from 50 mA to 1000 mA. When the battery is charged using USB power, charge currents of 100 mA or 500 mA are pin-selectable. The termination voltage is controlled to within ±0.35% of 4.2V.

The LM3658 requires few external components and integrates internal power FETs, reverse current protection and current sensing. The internal power FETs are thermally regulated to obtain the most efficient charging rate for a given ambient temperature.

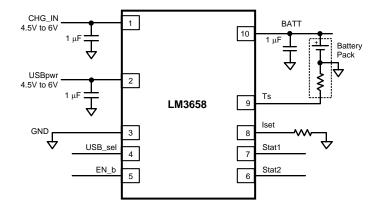
The LM3658 operates in five modes: pre-qualification mode, constant-current mode, constant-voltage mode, top-off mode and maintenance mode. Additionally, the charger IC operates as a linear regulator in "LDO mode", when the AC wall adapter is connected and no battery is present. Optimal battery management is obtained through thermal regulation, battery temperature measurement and multiple safety timers. The LM3658 provides two open-drain outputs for LED status indication or connection to GPIOs.



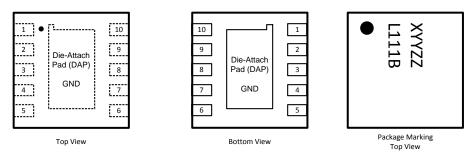
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# **Typical Application**



# **Connection Diagram and Package Mark Information**



**Note:** The actual physical placement of the package marking will vary from part to part. The package marking "X" is the manufacturing plant code. "YY" is a 2-digit date code, and "ZZ" for die traceability. These codes will vary considerably. "L111B" identifies the device (part number, option, etc.).

Figure 1. LLP10 Package Drawing

### **Pin Functions**

### **Pin Descriptions**

Pin#	Name	Description
1	CHG_IN	AC wall adapter input pin.
2	USBpwr	USB power input pin.
3	GND	Power and signal ground pin.
4	USB_sel	Pulling this pin low limits the USB charge current to 100 mA. Pulling this pin high limits the USB charge current to 500 mA.
5	EN_b	Pulling this pin low enables the charger. Pulling this pin high disables the charger.
6	STAT2	Active low open-drain output. Indicates charger status. This pin is capable of driving an LED as well as GPIOs. See Operation Description section for more detail.
7	STAT1	Active low open-drain output. Indicates charger status. This pin is capable of driving an LED as well as GPIO. See Operation Description section for more detail.
8	I <sub>SET</sub>	A resistor is connected between this pin and GND. The resistor value determines the full-rate charge current when using the AC source.
9	T <sub>S</sub>	Battery temperature sense pin. This pin must be connected to battery pack's temperature sense output pin. For the LM3658SD-B version, leaving this pin open indicates that the battery pack is not present. The charger IC will invoke LDO mode if this pin is left floating. See Operation Description section for more detail.
10	BATT	Positive battery terminal connection.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# Absolute Maximum Ratings (1) (2)

CHG_IN, USBpwr (V <sub>CC</sub> )	-0.3V to +6.5V
All other pins except GND	-0.3V to CHG_IN or USBpwr
Power Dissipation (3)	Internally Limited
Junction Temperature (T <sub>J-MAX)</sub>	+150°C
Storage Temperature Range	−65°C to +150°C
ESD Rating <sup>(4)</sup> Human Body Model: Machine Model:	2.0 kV 200V

- (1) All voltages are with respect to the potential at the GND pin.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is guaranteed. Operating Ratings do not imply guaranteed performance limits. For guaranteed performance limits and associated test conditions, see the Electrical Characteristics tables.
- (3) The LM3658 has built-in thermal regulation to regulate the die temperature to 120°C. See Operation Description section for more detail.
- (4) The Human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin. MIL-STD-883 3015.7

# Operating Ratings (1) (2)

Input Voltage Range for CHG_IN	4.5V to 6.0V
Input Voltage Range for USB_pwr	4.35V to 6.0V
Recommended Load Current	0 to 1000 mA
Power Dissipation (3)	Internally Limited
Junction Temperature (T <sub>J</sub> ) Range	−40°C to +125°C
Ambient Temperature (T <sub>A</sub> ) Range	−40°C to +85°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the component may occur. Operating Ratings are conditions under which operation of the device is guaranteed. Operating Ratings do not imply guaranteed performance limits. For guaranteed performance limits and associated test conditions, see the Electrical Characteristics tables.
- (2) All voltages are with respect to the potential at the GND pin.
- (3) The LM3658 has built-in thermal regulation to regulate the die temperature to 120°C. See Operation Description section for more detail.

# **Thermal Properties**

θ <sub>JA</sub> , Junction-to-Ambient Thermal	54°C/W
Resistance (1)	

(1) Junction-to-ambient thermal resistance is highly application and board-layout dependent. In applications where high maximum power dissipation exists, special care must be paid to thermal dissipation issues in board design. Please refer to application note AN1187 for more detail.

Product Folder Links: LM3658



# **Electrical Characteristics**

Unless otherwise noted,  $V_{CC}$  ( $V_{CHG\_IN}$  and/or  $V_{USBpwr}$ ) = 5V,  $V_{BATT}$  = 3.5V.  $C_{CHG\_IN}$  = 1  $\mu$ F,  $C_{USBpwr}$  = 1  $\mu$ F,  $C_{BATT}$  = 1  $\mu$ F. Typical values and limits appearing in normal type apply for  $T_J$  = 25°C. Limits appearing in **boldface** type apply over  $T_J$  = 0°C to +85°C. (1) (2) (3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
CHARGE	R			•	•	
V <sub>CHG_IN</sub>	AC Wall Adapter Input Voltage Range		4.5		6.0	V
$V_{USBpwr}$	USB Input Voltage Range		4.35		6.0	V
I <sub>CC_PD</sub>	Quiescent Current in Power Down Mode	V <sub>BATT</sub> > V <sub>CC</sub> -V <sub>OK_CHG</sub>	5	μΑ		
I <sub>CC_STBY</sub>	Quiescent Current in Standby Mode	V <sub>BATT</sub> < V <sub>CC</sub> - V <sub>OK_CHG</sub> V <sub>CC</sub> > V <sub>POR</sub> EN_b = High			600	μΑ
I <sub>BATT_PD</sub>	Battery Leakage Current in Power Down Mode	V <sub>BATT</sub> > V <sub>CC</sub> + V <sub>OK_CHG</sub>		0.01	2.0	μΑ
I <sub>BATT_MAI</sub> NT	Battery Leakage Current in Maintenance Mode	STAT1 = off, STAT2 = on, adapter or USB connected, $V_{BATT} = 4.2V$		7	15	μΑ
V <sub>OK_CHG</sub>	CHG_IN or USBpwr OK Trip- Point	V <sub>CC</sub> - V <sub>BATT</sub> (Rising) V <sub>CC</sub> - V <sub>BATT</sub> (Falling)		200 50		mV
V <sub>POR</sub>	V <sub>CC</sub> POR Trip- Point	V <sub>CC</sub> (Rising) VBATT < V <sub>CC</sub> - V <sub>OK_CHG</sub> VFULL_RATE < VBATT < VTERM		3.0		٧
V <sub>TERM</sub>	Battery Charge Termination Voltage	$I_{CHG}$ = 10% of its value when $V_{BATT}$ = 3.5V		4.2		٧
	Battery Charge	T <sub>A</sub> = 25°C	-0.35		+0.35	
	Termination Voltage Tolerance	$T_A = 0$ °C to 85°C	<b>−1.5</b>		+1.5	%
V <sub>CHG_DO</sub>	CHG_IN Drop-Out Voltage	V <sub>BATT</sub> = V <sub>TERM</sub> , I <sub>CHG</sub> = 1A V <sub>CC</sub> > V <sub>BATT</sub> + V <sub>CHG_DO_MAX</sub>		500		mV
$V_{USB\_DO}$	USBpwr Drop-Out Voltage	V <sub>BATT</sub> = V <sub>TERM</sub> , USB_sel = high V <sub>CC</sub> > V <sub>BATT</sub> + V <sub>USB_DO_MAX</sub>		250		mV
I <sub>CHG</sub>	CHG_IN Full-Rate Charge Current Range (see full- rate charge mode description)	$\begin{aligned} 6V &\geq V_{CC} \geq 4.5V \\ V_{BATT} &< V_{CC} - V_{OK\_CHG} \\ V_{FULL\_RATE} &< V_{BATT} < V_{TERM} \\ I_{CHG} &= K_{ISET}/R_{ISET} \end{aligned}$	50		1000	mA
$I_{\text{CHG}}$	CHG_IN Full Rate	$R_{ISET} = 10k\Omega$	220	245	270	
	Charge Current	$R_{ISET} = 5 \text{ k}\Omega$	465	500	535	mA
		$R_{ISET} = 3.3k\Omega$	700	760	820	
K <sub>ISET</sub>	Charge Current Set Coefficient I <sub>CHG</sub> = K <sub>ISET</sub> /R <sub>ISET</sub> (see full-rate charge mode description)	$6V \ge V_{CC} \ge 4.5V$ $V_{BATT} < V_{CC} - V_{OK\_CHG}$ $V_{FULL\_RATE} < V_{BATT} < V_{TERM}$		2500		ΑΩ
V <sub>ISET</sub>	Charge Current Set Voltage	$6V \ge V_{CC} \ge 4.5V$ $V_{BATT} < V_{CC} - V_{OK\_CHG}$ $V_{FULL\_RATE} < V_{BATT} < V_{TERM}$		2.5		٧

<sup>(1)</sup> All voltages are with respect to the potential at the GND pin.

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<sup>(2)</sup> Min and Max limits are guaranteed by design, test, or statistical analysis. Typical numbers are not guaranteed, but do represent the most likely norm.

<sup>(3)</sup> LM3658 is not intended as a Li-Ion battery protection device; battery used in this application should have an adequate internal protection.



# **Electrical Characteristics (continued)**

Unless otherwise noted,  $V_{CC}$  ( $V_{CHG\_IN}$  and/or  $V_{USBpwr}$ ) = 5V,  $V_{BATT}$  = 3.5V.  $C_{CHG\_IN}$  = 1  $\mu$ F,  $C_{USBpwr}$  = 1  $\mu$ F,  $C_{BATT}$  = 1  $\mu$ F. Typical values and limits appearing in normal type apply for  $T_J$  = 25°C. Limits appearing in **boldface** type apply over  $T_J$  = 0°C to +85°C. (1) (2) (3)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
I <sub>USB_L</sub>	USB Full-Rate Charge Low Current		80	90	100	mA
I <sub>USB_H</sub>	USB Full-Rate Charge High Current		400	450	500	mA
I <sub>PREQUAL</sub>	Pre-Qualification Current	V <sub>BATT</sub> = 2V, for both AC adapter and USB	35	45	55	mA
V <sub>FULL_RA</sub> TE	Full-Rate Qualification Threshold	V <sub>BATT</sub> rising, transition from prequalification to full-rate charging	2.9	3.0	3.1	V
	Full Rate Hysteresis	V <sub>BATT</sub> falling	50	60	70	mV
I <sub>EOC</sub>	End-of-Charge Current, Percent from Full-Range Current	$6V \ge V_{CC} \ge 4.5V$ $V_{BATT} < V_{CC} - V_{OK\_CHG}$ $V_{FULL\_RATE} < V_{BATT} < V_{TERM}$	7	9	11	%
I <sub>TOPOFF</sub>	Minimum Top-Off Charge Current	$6V \ge V_{CC} \ge 4.5V$ $V_{BATT} < V_{CC} - V_{OK\_CHG}$ $V_{BATT} = V_{TERM}$	1.25	2.5	3.75	%
V <sub>RESTART</sub>	Restart Threshold Voltage	V <sub>BATT</sub> falling, transition from EOC to pre-qualification mode	3.94	4.0	4.07	V
V <sub>TL</sub>	Battery Temperature Sense Comparator Low-Voltage Threshold		0.46	0.49	0.52	V
V <sub>TH</sub>	Battery Temperature Sense Comparator High-Voltage Threshold		2.44	2.49	2.54	V
I <sub>TSENSE</sub>	Battery Temperature Sense Current		94	100	106	μΑ
T <sub>REG</sub>	Regulated Junction Temperature			120		°C
T <sub>SD</sub>	Thermal Shutdown Temperature			165		°C
$V_{TLDO}$	LDO mode detection threshold	TS pin voltage for entry into LDO mode. For LM3658SD-B only	3.95	4.0		V
$V_{LDO}$	LDO Mode Regulation	$  6V \ge V_{CHG\_IN} \ge 4.5V                                   $	-3.0	4.2	+3.0	%
DETECTION	ON AND TIMING					
T <sub>POK</sub>	Power OK Deglitch Time	V <sub>BATT</sub> < V <sub>CC</sub> - V <sub>OK_CHG</sub>	40	60	100	ms
T <sub>PREQUAL</sub>	Pre-Qualification Timer		27	30	33	mins
T <sub>PQ_FULL</sub>	Deglitch Time for Pre-Qualification to Full-Rate Charge Transition		270	300	330	ms

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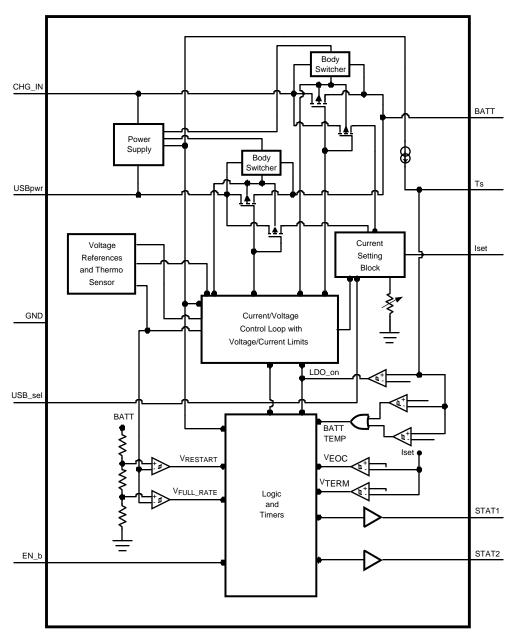
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Symbol	Parameter	Conditions	Min	Тур	Max	Units
T <sub>FULL_PQ</sub>	Deglitch Time for Full-Rate to Pre-Qualification Transition		270	300	330	ms
T <sub>CHG</sub>	Charge Timer	LM3658SD, LM3658SD-B and LM3658SD-A with USB_sel=high	270	300	330	mins
		LM3658SD-A with USB_sel=low	540	600	660	
T <sub>EOC</sub>	Deglitch Time for End-of-Charge Transition		270	300	330	ms
T <sub>BATTEMP</sub>	Deglitch Time for Battery Temperature Fault		20	40	80	ms
T <sub>DGL</sub>	Deglitch Time for EN_b and USB_sel Pins		20	40	80	ms
T <sub>ITOPOFF</sub>	Deglitch Time for I <sub>TOPOFF</sub>		270	300	330	ms
$T_{TOPOFF}$	Top-Off Charging Timer	LM3658SD, LM3658SD-B and LM3658SD-A with USB_sel=high	27	30	33	mins
		LM3658SD-A with USB_sel=low	54	60	66	
I/O						
V <sub>IL</sub>	Low-Level Input	EN_b	0		0.7	V
	Voltage	USB_sel			1.5	
V <sub>IH</sub>	High-Level Input	EN_b	1.4			V
	Voltage	USB_sel	2.5			
I <sub>OL</sub>	Low-Level Output Current	STAT1, STAT2, output voltage = 0.25V	10	25		mA
I <sub>OH</sub>	High-Level Output Current	STAT1, STAT2, output voltage = 6.0V		0.01	1	μA

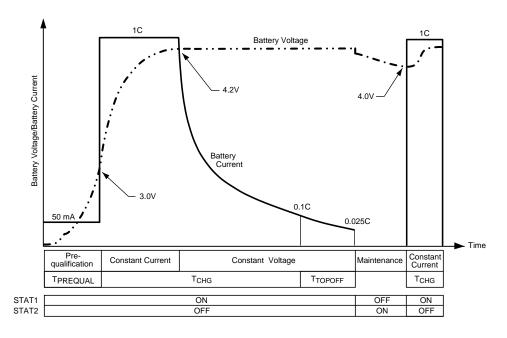


# **Block Diagram**





# Li-Ion Charging Profile



### **LM3658 Operation Description**

### **POWER-DOWN MODE**

The LM3658 will power down automatically when the voltage on the USBpwr or CHG\_IN pin drops below the battery voltage with an amount that is equal to  $V_{OK\_CHG}$  ( $V_{BATT} > V_{CC} - V_{OK\_CHG}$ ). Power-Down mode shuts off the internal power FETs as well as the open-drain pull-down transistors on the status pins STAT1 and STAT2. The only current consumed by the LM3658 is an ultra-low guiescent current of 1  $\mu$ A typical.

### **POWER-ON RESET**

As soon as the voltage of one of the power sources rises above  $V_{BATT} + V_{OK\_CHG}$ , the charger will wake up. However, charging will not be initiated unless the supply voltage source exceeds the  $V_{POR}$ .

### **AUTOMATIC POWER SOURCE DETECTION**

When the voltage of one of the power sources exceeds the  $V_{POR}$  threshold, the LM3658 detects which power source is a valid charge supply. When both supply voltages are valid and present, CHG\_IN will automatically be selected over USBpwr. The USBpwr will be the designated power source only if no CHG\_IN is present or when the voltage on the CHG\_IN pin is less than the battery voltage.

### THERMAL POWER FET REGULATION

The internal power FETs are thermally regulated to the junction temperature of  $120^{\circ}$ C to guarantee optimal charging of the battery. At all times is the charge current limited by the  $I_{SET}$  resistor setting, the USB 100 mA/500 mA selection, or the  $100^{\circ}$ C junction temperature of the LM3658. The charge current is therefore a function of the charge current settings, the thermal conductivity of the package and the ambient temperature as described in the following equation:

Where  $T_A$  is the ambient temperature and  $\theta_{JA}$  is the thermal resistance of the package. Thermal regulation guarantees maximum charge current and superior charge rate without exceeding the power dissipation limits of the LM3658.



### **PRE-QUALIFICATION MODE**

During pre-qualification, STAT1 is on and STAT2 is off, and the charger supplies a constant current of 50 mA to the battery. When the battery voltage reaches  $V_{FULL\_RATE}$ , the charger transitions from pre-qualification to full-rate charging. The pre-qualification mode aborts when the battery doesn't reach  $V_{FULL\_RATE}$  within the time allowed in  $T_{PREQUAL}$  timer. In this event, charging stops and STAT1 and STAT2 will both be on, indicating a bad battery condition.

### CHG IN FULL-RATE CHARGING MODE

The full-rate charge cycle is initiated following the successful completion of the pre-qualification mode. Timer  $T_{CHG}$  starts to count when the charger enters full-rate charging, with STAT1 on and STAT2 off. When charging with an AC wall adapter, the full-rate charge current is proportional to the value of the resistor that is connected to the  $I_{SFT}$  pin as described in the following equation:

$$I_{CHG} = \frac{K_{ISET}}{R_{ISET}} \tag{1}$$

It is recommended to charge Li-Ion batteries at 1C rate, where "C" is the capacity of the battery. As an example, it is recommended to charge a 750 mAh battery at 750 mA, or 1C. Charging at a higher rate can cause damage to the battery.

### **USBpwr FULL-RATE CHARGING MODE**

The full-rate charge cycle is initiated following the successful completion of the pre-qualification mode. Timer  $T_{CHG}$  starts to count when the charger enters full-rate charging, with STAT1 on and STAT2 off. If the USB bus provides the charger supply, then the default full-rate charge current is 100 mA max unless the USB\_sel pin is pulled high, which sets the charge current to 500 mA max.

### CONSTANT-VOLTAGE CHARGING MODE AND END-OF-CHARGE (EOC) DETECTION

The battery voltage increases rapidly as a result of full-rate charging and will reach the 4.2V termination voltage, triggering the constant-voltage charge cycle. Timer  $T_{CHG}$  continues to count in this cycle. STAT1 is on and STAT2 is off. The charge current gradually decreases during constant-voltage charging until it reaches the End-Of-Charge (EOC), which is equal to 10% of the full-rate current set either by the resistor connected to the  $I_{SET}$  pin or the USB\_sel pin. If Timer  $T_{CHG}$  times out before EOC is reached, charging stops and STAT1 and STAT2 will both be on, indicating a bad battery condition.

### **TOP-OFF CHARGING MODE**

Once EOC has been reached, a top-off cycle continues to charge the battery. Timed top-off cycle provides optimal battery capacity following a complete charge cycle. During this cycle, charging terminates when I<sub>CHG</sub> reaches 2.5% of the full-rate charge current or when T<sub>TOPOFF</sub> times out, whichever occurs first. STAT1 will turn off and STAT2 will turn on once the top-off cycle completes successfully, indicating that charging is done.

### **MAINTENANCE MODE**

Maintenance mode begins immediately after the charger successfully finishes the top-off cycle. In the maintenance mode, the battery voltage is being monitored by the LM3658 continuously. If the battery voltage drops 200 mV below  $V_{\text{TERM}}$ , a new full-rate charge cycle starts to replenish the battery. As this new full-rate charge cycle begins, STAT1 will turn on and STAT2 will turn off, and all the timers will reset. Refer to the LM3658 Flowchart.

### **CHARGE STATUS OUTPUTS**

The LM3658 provides two open-drain outputs STAT1 and STAT2 that can be connected to external LEDs or to General Purpose I/O's (GPIO) of a peripheral IC. All charge status of the LM3658 is illustrated in Table 1. "ON" means that STATx pin is pulled low as its pull-down transistor is turned on, representing a logic 0.

**Table 1. Status Pins Summary** 

STAT1	STAT2	Condition			
OFF	OFF	Power-Down, charging is suspended or interrupted			

Product Folder Links: LM3658



### **Table 1. Status Pins Summary (continued)**

STAT1	STAT2	Condition
ON	OFF	Pre-qualification mode, CC and CV charging, Top-off mode
OFF	ON	Charge is completed
ON	ON	Bad battery (Safety timer expired), or LDO mode

### **SAFETY TIMERS**

In order to prevent endless charging of the battery, which can cause damage to the battery, there are three safety timers that forcefully terminate charging if the charging mode is not completed within the time allowed.

### **Pre-Qualification Timer (T**<sub>PREQUAL</sub>)

The pre-qualification timer starts with the initiation of the pre-qualification mode and allows 30 minutes to transition from pre-qualification to full rate charging. If the battery voltage does not reach  $V_{\text{FULL\_RATE}}$  in 30 minutes, charging stops and status pins STAT1 and STAT2 both turn on to indicate a bad battery status.

### Charger Timer (T<sub>CHG</sub>)

The charge timer starts with the initiation of full-rate charging and has a duration of 5 hours for the LM3658. If the charge current does not reach EOC, charging stops and STAT1 and STAT2 both turn on to indicate a bad battery status. Once the charge control declares a bad battery, removing the input source is the only means to clear the bad battery status.

### **Top-Off Timer (** $T_{TOPOFF}$ **)**

Once the charger successfully completes constant current constant voltage charging, it enters top-off mode and starts  $T_{TOPOFF}$  timer. Topoff lasts 30 minutes for the LM3658. During top-off, charging stops when  $T_{TOPOFF}$  reaches its count or when  $I_{CHG}$  reaches 2.5% of the full-rate charge current. There is no time-out condition in top-off mode.

When charging is interrupted either by battery temperature out of range or disabling the LM3658, the applicable safety timer will store its count value for the duration of the interruption and subsequently resumes counting from its stored count value when charging continues, only if the charger resumes to the same operation mode it was in before the interrupt.

The LM3658SD-A version has selectable timers for  $T_{CHG}$  and  $T_{TOPOFF}$ . Based on the logic level applied to the USB\_sel pin, timers can be chosen as follow:

Input	USB_SEL	T <sub>PREQUAL</sub>	T <sub>CHG</sub>	T <sub>TOPOFF</sub>
CHG_IN	Low	30 minutes	10 hours	60 minutes
CHG_IN	High	30 minutes	5 hours	30 minutes
USBpwr	Low	30 minutes	10 hours	60 minutes
USBpwr	High	30 minutes	5 hours	30 minutes

# **BATTERY TEMPERATURE MONITORING (SUSPEND MODE)**

The LM3658 is equipped with a battery thermistor interface to continuously monitor the battery temperature by measuring the voltage between the  $T_S$  pin and ground. Charging is allowed only if the battery temperature is within the acceptable temperature range set by a pair of internal comparators inside the LM3658. If the battery temperature is out of range, STAT1 and STAT2 both turn off and charging is suspended. Timer holds its count value.

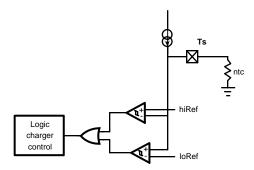
The TS pin is only active during charging and draws no current from the battery when no external power source is present.

If the TS pin is not used in the application, it should be connected to GND through  $10k\Omega$  pulldown resistor.

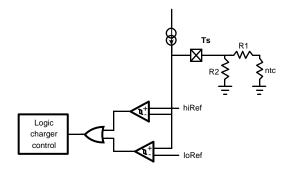
When the TS pin is left floating (battery removal), then the charger will be disabled as the TS voltage exceeds the upper temperature limit.

Product Folder Links: LM3658





The LM3658 battery temperature feature is tailored to use negative temperature coefficient (NTC) 103AT thermistors with  $10k\Omega$  impedance. If alternative thermistors need to be used in the system, supplemental external resistors are needed to create a circuit with equivalent impedance.



### **DISABLING CHARGER (CHARGE INTERRUPT MODE)**

Charging can be safely interrupted by pulling the EN\_b pin high and charging can resume upon pulling the EN\_b pin low. The enable pin can be permanently tied to GND with no extra current consumption penalty during power down mode. When the charger is disabled, timer holds its count value, and STAT1 and STAT2 are both off.

### LDO MODE (AVAILABLE ONLY IN LM3658SD-B VERSION)

The LM3658SD-B version enters LDO mode when the  $T_s$  pin is floating and AC wall adapter is still connected to CHG\_IN pin. In LDO mode, STAT1 and STAT2 are both on. The LM3658SD-B becomes a linear regulator capable of delivering 1A of source current. Normally the  $T_s$  pin is connected to the thermistor from the battery pack for temperature monitoring purpose. If this pin is disconnected, the LM3658SD-B assumes that there is no battery present and will automatically invoke the LDO mode. LDO mode allows applications to operate without a battery provided that the AC wall adapter supplies power to the CHG\_IN pin. The LDO mode is not possible in USB mode.

For the other versions of the LM3658, floating the T<sub>s</sub> pin does not invoke LDO mode. Instead, it will go to suspend mode. Please refer to "Battery Temperature Monitoring" section for more detail.

# 5 HOUR/ 10 HOUR SELECTABLE TIMER (AVAILABLE ONLY IN LM3658SD-A VERSION)

The LM3658SD-A allows the user to select between 5 hour or 10 hour timer based on the polarity of the USB\_sel pin, in both CHG\_IN mode and USBpwr mode. By pulling the USB\_sel pin high, the timer is set to 5 hours. In the USBpwr mode, the polarity of the USB\_sel pin determines the charge current as well as the timer. In CHG\_IN mode, the polarity of the USB\_sel pin determines only the timer. The charge current is set by the resistor at I<sub>set</sub> pin.

### INPUT/OUTPUT BYPASS CAPACITORS

Care should be taken to support the stability of the charge system by connecting a 1  $\mu$ F capacitor as close as possible to the BATT pin. An input capacitor ranging from 1.0  $\mu$ F – 10.0  $\mu$ F must be connected to the CHG\_IN and USBpwr input pins. Low cost ceramic capacitors can be selected.

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### THERMAL PERFORMANCE OF THE LLP PACKAGE

The LM3658 is a monolithic device with integrated power FETs. For that reason, it is important to pay special attention to the thermal impedance of the LLP package and to the PCB layout rules in order to maximize power dissipation of the LLP package.

The LLP package is designed for enhanced thermal performance and features an exposed die attach pad at the bottom center of the package that creates a direct path to the PCB for maximum power dissipation. Compared to the traditional leaded packages where the die attach pad is embedded inside the molding compound, the LLP reduces one layer in the thermal path.

The thermal advantage of the LLP package is fully realized only when the exposed die attach pad is soldered down to a thermal land on the PCB board with thermal vias planted underneath the thermal land. Based on thermal analysis of the LLP package, the junction-to-ambient thermal resistance ( $\theta_{JA}$ ) can be improved by a factor of two when the die attach pad of the LLP package is soldered directly onto the PCB with thermal land and thermal vias, as opposed to an alternative with no direct soldering to a thermal land. Typical pitch and outer diameter for thermal vias are 1.27 mm and 0.33 mm respectively. Typical copper via barrel plating is 1 oz, although thicker copper may be used to further improve thermal performance. The LM3658 die attach pad is connected to the substrate of the IC and therefore, the thermal land and vias on the PCB board need to be connected to ground (GND pin).

For more information on board layout techniques, refer to Application Note 1187 "Leadless Lead Frame Package (LLP)." This application note also discusses package handling, solder stencil and the assembly process.



### **LM3658 FLOWCHARTS**

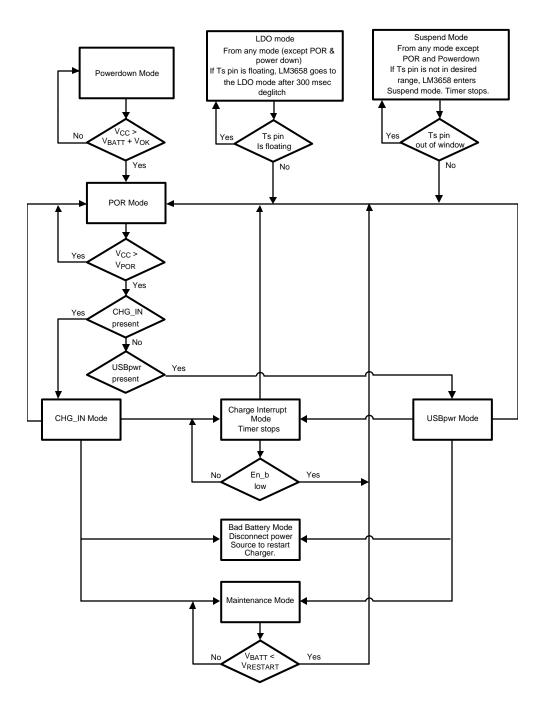


Figure 2. LM3658 Flowchart



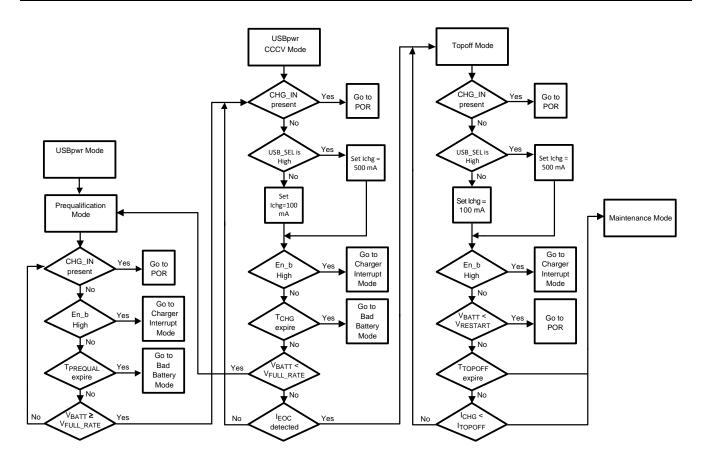


Figure 3. LM3658 USBpwr Mode Flowchart

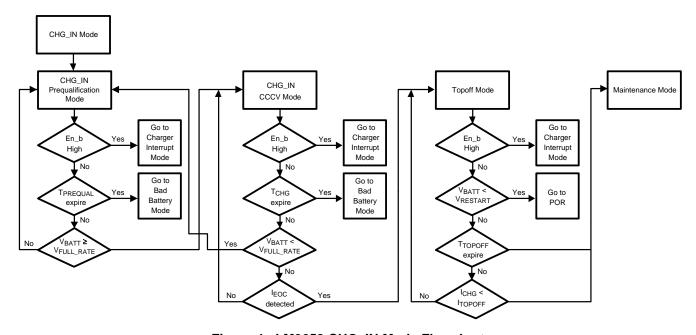


Figure 4. LM3658 CHG\_IN Mode Flowchart





9-Mar-2013

### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
LM3658SD	ACTIVE	WSON	DSC	10	1000	TBD	Call TI	Call TI	-40 to 85	L111B	Samples
LM3658SD-A/NOPB	ACTIVE	WSON	DSC	10	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L155B	Samples
LM3658SD-B	ACTIVE	WSON	DSC	10	1000	TBD	Call TI	Call TI	-40 to 85	L156B	Samples
LM3658SD-B/NOPB	ACTIVE	WSON	DSC	10	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L156B	Samples
LM3658SD/NOPB	ACTIVE	WSON	DSC	10	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L111B	Samples
LM3658SDX	ACTIVE	WSON	DSC	10	4500	TBD	Call TI	Call TI	-40 to 85	L111B	Samples
LM3658SDX-A	ACTIVE	WSON	DSC	10	4500	TBD	Call TI	Call TI	-40 to 85	L155B	Samples
LM3658SDX-A/NOPB	ACTIVE	WSON	DSC	10	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L155B	Samples
LM3658SDX-B	ACTIVE	WSON	DSC	10	4500	TBD	Call TI	Call TI	-40 to 85	L156B	Samples
LM3658SDX-B/NOPB	ACTIVE	WSON	DSC	10	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L156B	Samples
LM3658SDX/NOPB	ACTIVE	WSON	DSC	10	4500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L111B	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



# **PACKAGE OPTION ADDENDUM**

9-Mar-2013

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

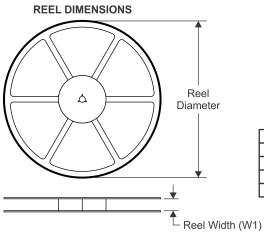
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**PACKAGE MATERIALS INFORMATION** 

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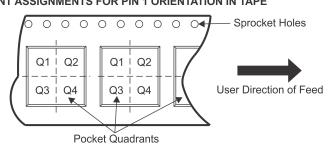
# TAPE AND REEL INFORMATION



# TAPE DIMENSIONS KO P1 BO W Cavity AO

	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

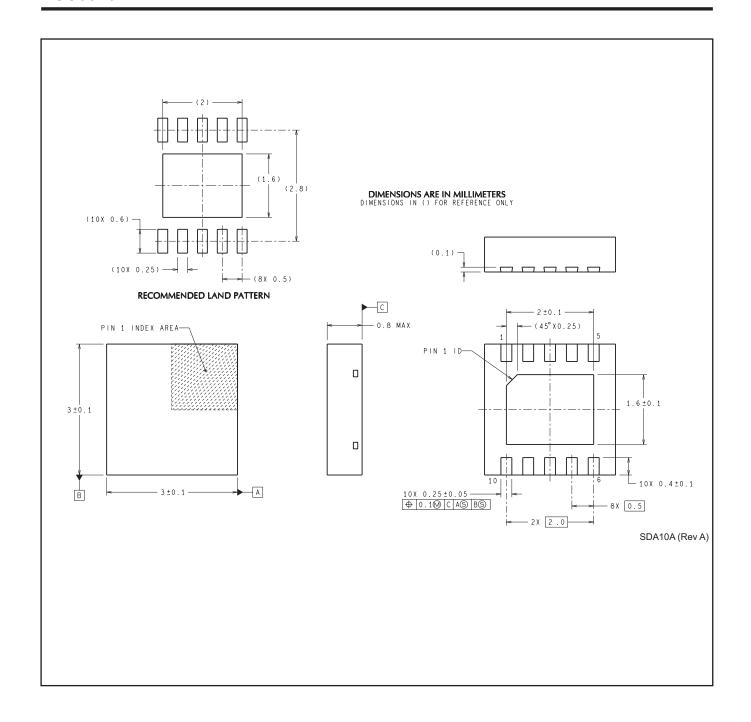
All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM3658SD	SON	DSC	10	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SD-A/NOPB	SON	DSC	10	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SD-B	SON	DSC	10	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SD-B/NOPB	SON	DSC	10	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SD/NOPB	SON	DSC	10	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX-A	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX-A/NOPB	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX-B	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX-B/NOPB	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
LM3658SDX/NOPB	SON	DSC	10	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM3658SD	SON	DSC	10	1000	203.0	190.0	41.0
LM3658SD-A/NOPB	SON	DSC	10	1000	203.0	190.0	41.0
LM3658SD-B	SON	DSC	10	1000	203.0	190.0	41.0
LM3658SD-B/NOPB	SON	DSC	10	1000	203.0	190.0	41.0
LM3658SD/NOPB	SON	DSC	10	1000	203.0	190.0	41.0
LM3658SDX	SON	DSC	10	4500	349.0	337.0	45.0
LM3658SDX-A	SON	DSC	10	4500	349.0	337.0	45.0
LM3658SDX-A/NOPB	SON	DSC	10	4500	349.0	337.0	45.0
LM3658SDX-B	SON	DSC	10	4500	349.0	337.0	45.0
LM3658SDX-B/NOPB	SON	DSC	10	4500	349.0	337.0	45.0
LM3658SDX/NOPB	SON	DSC	10	4500	349.0	337.0	45.0



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